

cc



PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date August 23, 2007 A Beggs
Alexandra Beggs

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Dinish Chopra and Scott G. Meikle Attorney Docket No.: 500077.12
Patent No. : US 6,964,602 B2 Serial No. : 10/810,036
Issue Date : November 15, 2005 Filed : March 26, 2004
Title : METHODS AND APPARATUSES FOR MECHANICAL AND CHEMICAL-MECHANICAL PLANARIZATION OF MICROELECTRONIC-DEVICE SUBSTRATE ASSEMBLIES ON PLANARIZING PADS

REQUEST FOR CERTIFICATE OF CORRECTION

Certificate
AUG 30 2007
of Correction

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

A Certificate of Correction under 35 U.S.C. § 254 is respectfully requested for the above-identified patent in order to correct Patent and Trademark Office errors made during the printing of the patent. The changes in the patent needed to correct the errors are as follows:

<u>Column, Line</u>	<u>Reads</u>	<u>Should Read</u>
Item (57), Line 20	"includes removing unit"	--includes a removing unit--
Column 2, Line 9	"C—C the substrate 12."	--C—C of the substrate 12.--
Column 2, Line 65	"is over planarized,"	--is over-planarized,--
Column 6, Lines 22 and 27	"the first-stage"	--the first stage--

AUG 30 2007

Column 7, Line 64 "the substrate The multi- --the substrate. The multi-stage--
stage"

The above errors for which correction is requested under 35 U.S.C. § 254 were made in the printing of the patent or in the original application. The errors are considered sufficiently important to justify the processing of a Certificate of Correction under 35 U.S.C. § 254. A Form PTO-1050, in duplicate, is enclosed herewith.

The Commissioner is hereby authorized to charge payment of any fees associated with this communication to Deposit Account No. 50-1266. A duplicate copy of this sheet is enclosed.

Favorable consideration of this Request is respectfully requested.

Respectfully submitted,

Date:

Aug. 21. 2007

By:



Edward W. Bulchis, Reg. No. 26,847

Customer No. 27,076

Dorsey & Whitney LLP

1420 Fifth Avenue, Suite 3400

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Attorney for Applicant(s)

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Enclosures:

Postcard

Form PTO-1050 (+ copy)

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AUG 30 2007

**UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION**

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DATED : November 15, 2005
INVENTOR(S) : Dinesh Chopra and Scott G. Meikle

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MAILING ADDRESS OF SENDER:

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Patent No. US 6,964,602 B2

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FORM PTO-1050 (REV. 3-82)

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